华田信科电子有限公司

HTDISPLAY ELECTRONICS CO.,LTD.

The professional LCD manufacturer

www.htdisplay.com

SPECIFICATIONS

Product Name: LCM

Model PartNumber: HT240022A

Revision: R00 Date: 2017-5-15

Prepared By:	Reviewed By:	Approved By:
HT		

Customer: _____

Custoer Approved Result: _____ □ OK □ NG _____

Custoer Confirmed Message: _____

_____

Approved By: _____ Date: _____

Records of Revision

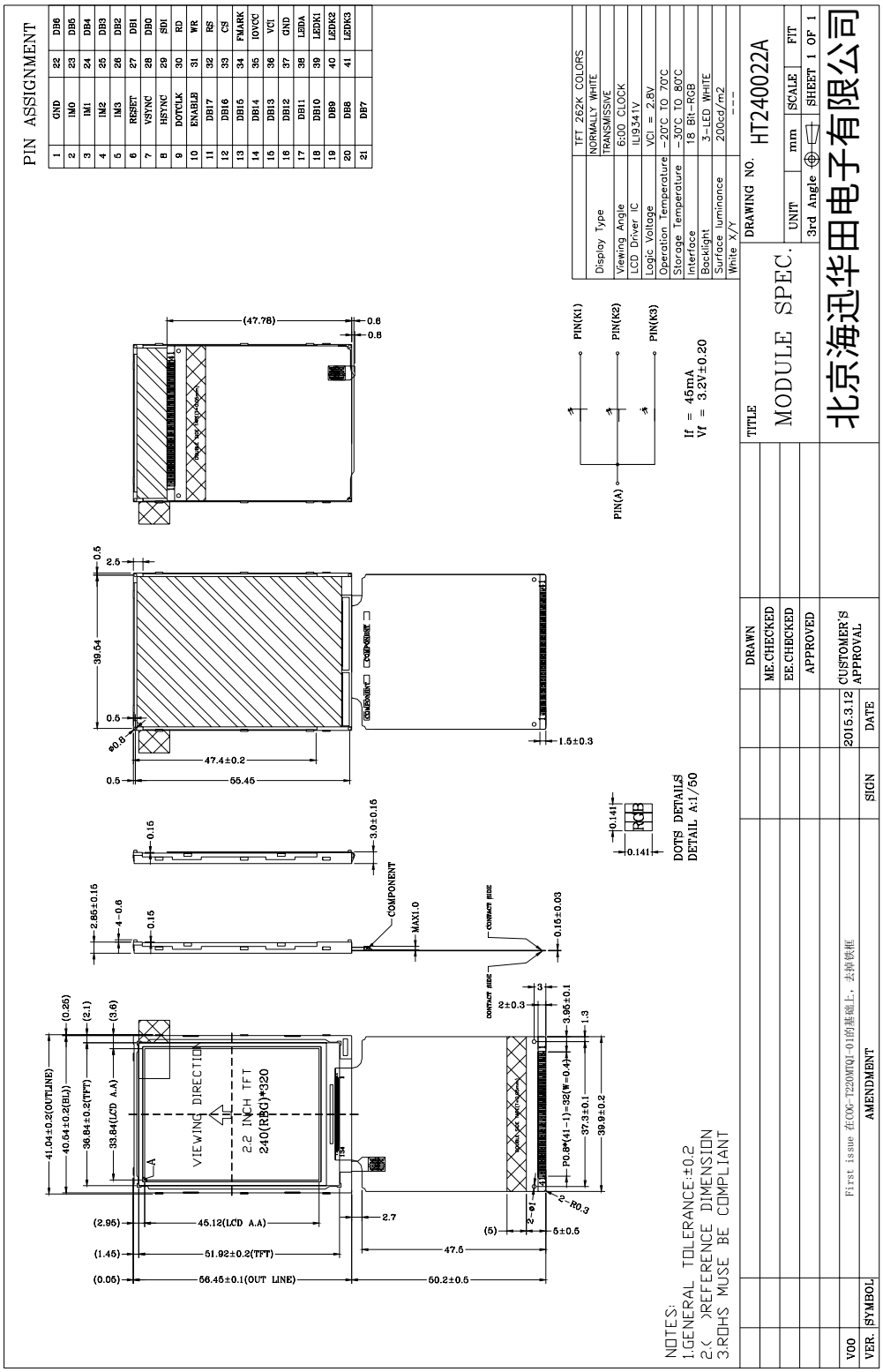
DATE	REF.PAGE PARAGRAPH DRAWING No.	REVISED No.	SUMMARY	REMARK

Contents

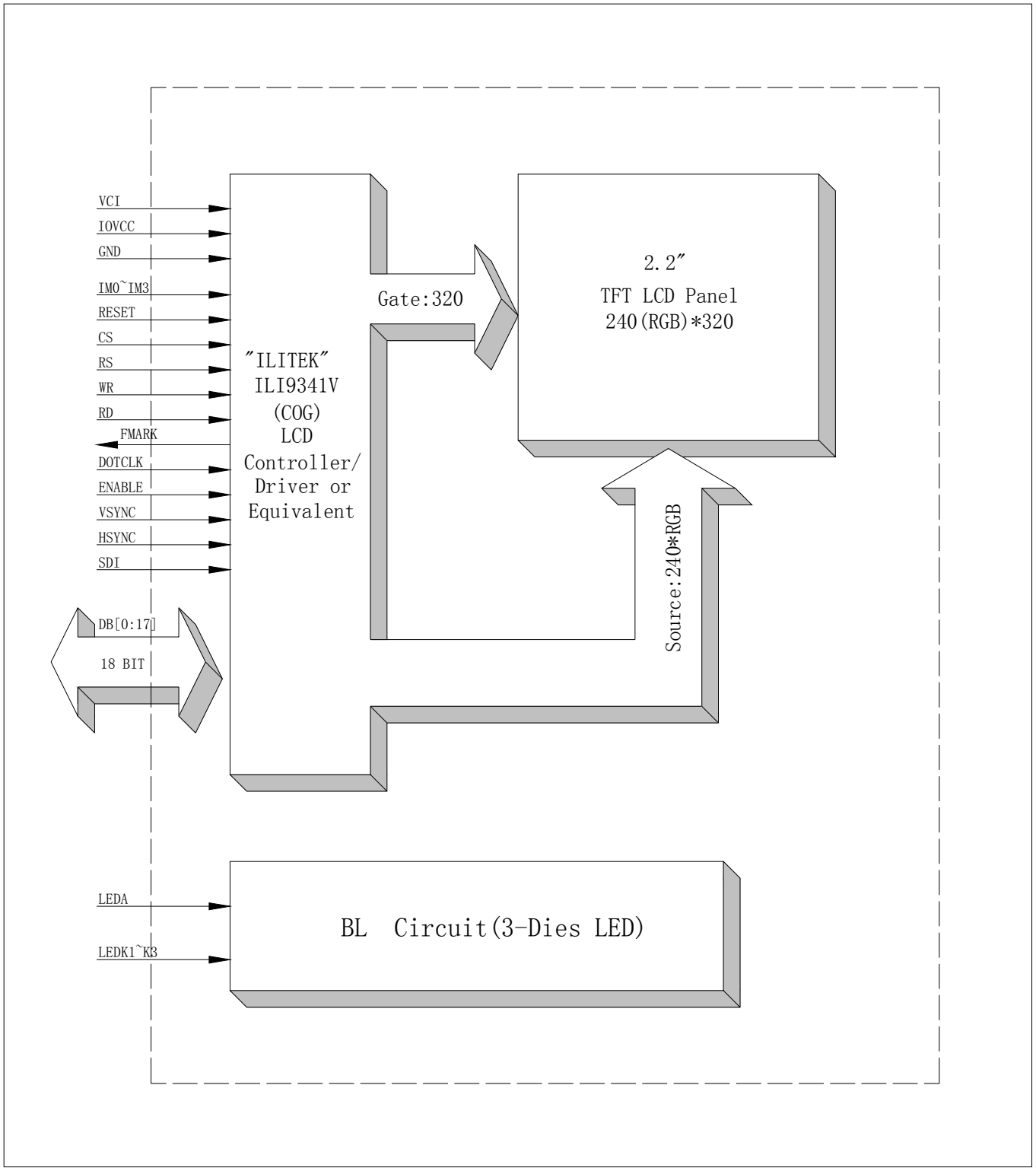
1. General Specification

Item	Contents	Unit
LCD TYPE	TFT/TRANSMISSIVE	
MODULE SIZE (W*H*T)	41.04*56.45*2.85	MM
ACTIVE SIZE (W*H)	33.84*45.12	MM
PIXEL PITCH (W*H)	0.141*0.141	MM
NUMBER OF DOTS	240*320	
DIVER IC	ILI9341V	
INTERFACE TYPE	18-BIT RGB/MCU	
TOP POLARIZER TYPE	GLARE	
RECOMMEND VIEWING DIRECTION	6	O'CLOCK
GRAY SCALE INVERSION DIRECTION	12	O'CLOCK
COLORS	262K	
BACKLIGHT TYPE	3-DIES WHITE LED	
TOUCH PANEL TYPE	WITHOUT	

2. Mechanical Drawing



3. Block Diagram



4. Interface Pin Function

Pin No.	Symbol	Description
1	GND	Power ground
2~5	IM0~IM3	Select the MCU interface mode. Fix this pin at IOVCC or GND. *** Note**
6	RESET	This signal will reset the device and must be applied to properly initialize the chip. Signal is active low.
7	VSYNC	Frame synchronizing signal for RGB interface operation. Fix to IOVCC or GND level when not in use.
8	HSYNC	Line synchronizing signal for RGB interface operation. Fix to IOVCC or GND level when not in use.
9	DOTCLK	Dot clock signal for RGB interface operation. Fix to IOVCC or GND level when not in use.
10	ENABLE	Data enable signal for RGB interface operation. Fix to IOVCC or GND level when not in use.
11~28	DB17~DB0	Data bus
29	SDI	When IM[3] : Low, Serial in/out signal. When IM[3] : High, Serial input signal. The data is applied on the rising edge of the SCL signal. If not used, fix this pin at IOVCC or GND.
30	RD	8080- /808Ⅰ 0-Ⅱ system (RDX): Serves as a read signal and MCU read data at the rising edge. Fix to IOVCC level when not in use.
31	WR	(WRX) - 8080-Ⅰ/8080-Ⅱ system: Serves as a write signal and writes data at the rising edge. (D/CX) - 4-line system: Serves as the selector of command or parameter. Fix to IOVCC level when not in use.
32	RS	(D/CX): This pin is used to select “Data or Command” in the parallel interface. When DCX = 1, data is selected. When DCX = 0, command is selected. (SCL): This pin is used as the serial interface clock in 3-wire 9-bit/4-wire 8-bit serial data interface. If not used, this pin should be connected to IOVCC or GND.
33	CS	Chip select input pin (“Low” enable). This pin can be permanently fixed “Low” in MPU interface mode only.
34	FMARK	Tearing effect output pin to synchronize MPU to frame writing, activated by S/W command. When this pin is not activated, this pin is low. If not used, open this pin.
35	IOVCC	Power supply for logic.
36	VCI	Power supply for analog.
37	GND	Power ground

38	LEDA	Anode of LED backlight
39~41	LEDK1~K3	Cathode of LED backlight

Note: Select the MCU interface mode.

MPU Parallel interface bus and serial interface select

If use RGB Interface must select serial interface.

IM3	IM2	IM1	IM0	MCU-Interface Mode	DB Pin in use	
					Register/Content	GRAM
0	0	0	0	80 MCU 8-bit bus interface Ⅰ	D[7:0]	D[7:0]
0	0	0	1	80 MCU 16-bit bus interface Ⅰ	D[7:0]	D[15:0]
0	0	1	0	80 MCU 9-bit bus interface Ⅰ	D[7:0]	D[8:0]
0	0	1	1	80 MCU 18-bit bus interface Ⅰ	D[7:0]	D[17:0]
0	1	0	1	3-wire 9-bit data serial interface Ⅰ	SDA: In/OUT	
0	1	1	0	4-wire 8-bit data serial interface Ⅰ	SDA: In/OUT	
1	0	0	0	80 MCU 16-bit bus interface Ⅱ	D[8:1]	D[17:10], D[8:1]
1	0	0	1	80 MCU 8-bit bus interface Ⅱ	D[17:10]	D[17:10]
1	0	1	0	80 MCU 18-bit bus interface Ⅱ	D[8:1]	D[17:0]
1	0	1	1	80 MCU 9-bit bus interface Ⅱ	D[17:10]	D[17:9]
1	1	0	1	3-wire 9-bit data serial interface Ⅱ	SDI: In SDO: Out	
1	1	1	0	4-wire 8-bit data serial interface Ⅱ	SDI: In SDO: Out	

5. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Supply voltage for analog	VCI	-0.3	4.6	V
Supply voltage for logic	IOVCC	-0.3	4.6	V
Supply current (One LED)	I_{LED}		30	mA
Operating temperature	T_{OP}	-20	+70	°C
Storage temperature	T_{ST}	-30	+80	°C

Note : The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

6. Electrical Characteristics

6.1 Input Power

Item	Symbol	Min	Typ.	Max	Unit	Applicable terminal
Supply Voltage for Analog	VCI	2.5	2.8	3.3	V	
Supply Voltage for Logic	IOVCC	1.65	1.8/2.8	3.3	V	
Input Voltage	V_{IL}	GND	-	0.3IOVCC	V	
	V_{IH}	0.8 IOVCC	-	IOVCC		
Input leakage Current	I_{LKG}	-1		1	μA	

6.2 Backlight Driving Conditions

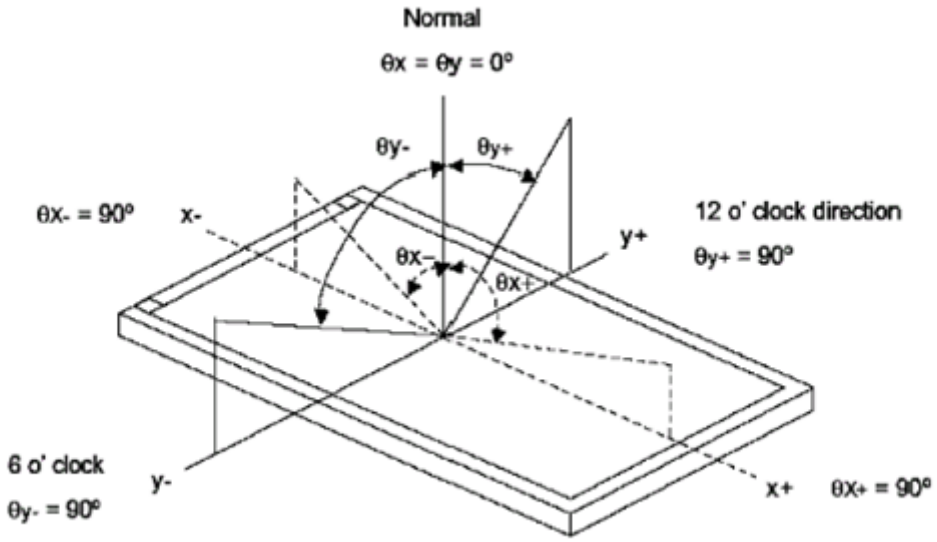
Item	Symbol	Value			Unit	Remark
		Min.	Typ.	Max.		
Voltage for LED Backlight	V_F	-	3.2	-	V	I_L =45mA
Current for LED Backlight	I_L		45	-	mA	
Power Consumption	P		0.144		W	
LED Life Time		30,000			Hr	Note

Note: Brightness to be decreased to 50% of the initial value at ambient temperature TA=25℃

7. Optical Characteristics

ITEM		SYMBOL	CONDITIONS	SPECIFICATIONS			UNIT	NOTE
				MIN	TYP.	MAX		
Luminance		L	I_L =45mA		200		Cd/m^2	
Contrast Ratio		CR	θ=0°	250	350			
Response Time		T_{ON}	25℃		20	30	ms	
		T_{OFF}						
CIE Color Coordinate	Red	X_R	Viewing normal angle		--			
		Y_R			--			
	Green	X_G			--			
		Y_G			--			
	Blue	X_B			--			
		Y_B			--			
	White	X_W		0.290	0.310	0.330		
		Y_W		0.310	0.330	0.350		
Viewing Angle	Hor.	θ_{X+}	CR≥10	40	45		Degree	
		θ_{X-}		40	45			
	Ver.	θ_{Y+}		45	50			
		θ_{Y-}		15	20			
Uniformity	Un			80			%	

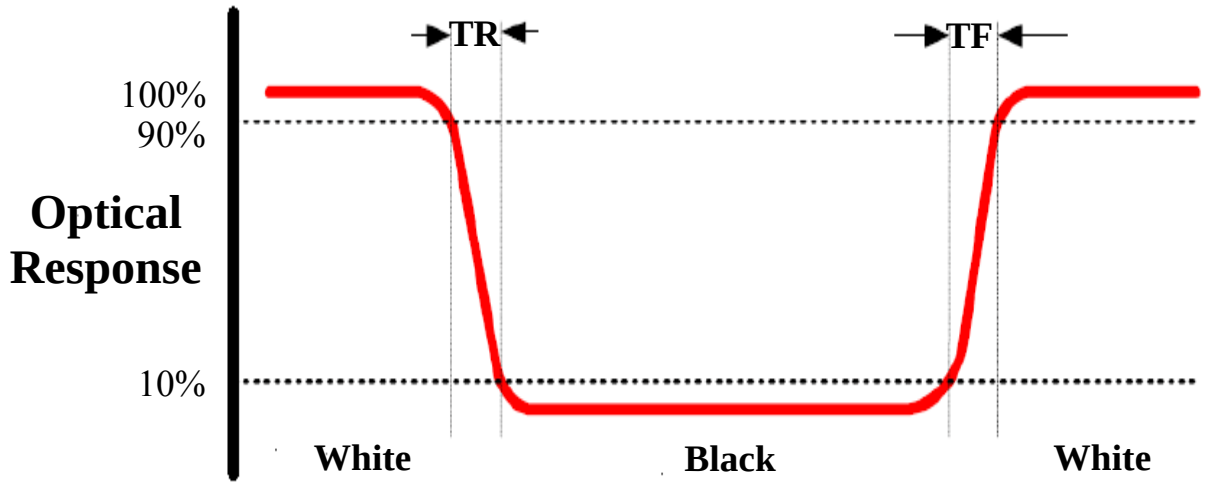
Note 1: Definition of Viewing Angle θx and θy:



Note 2: Definition of contrast ratio CR:

$$CR = \frac{\text{Luminance of white state}}{\text{Luminance of black state}}$$

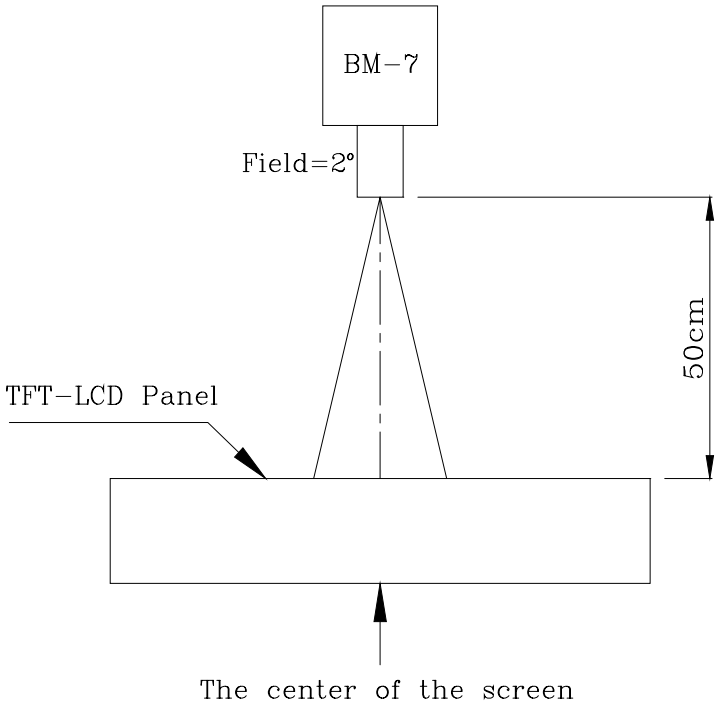
Note 3: Definition of Response Time(Tr,Tf)



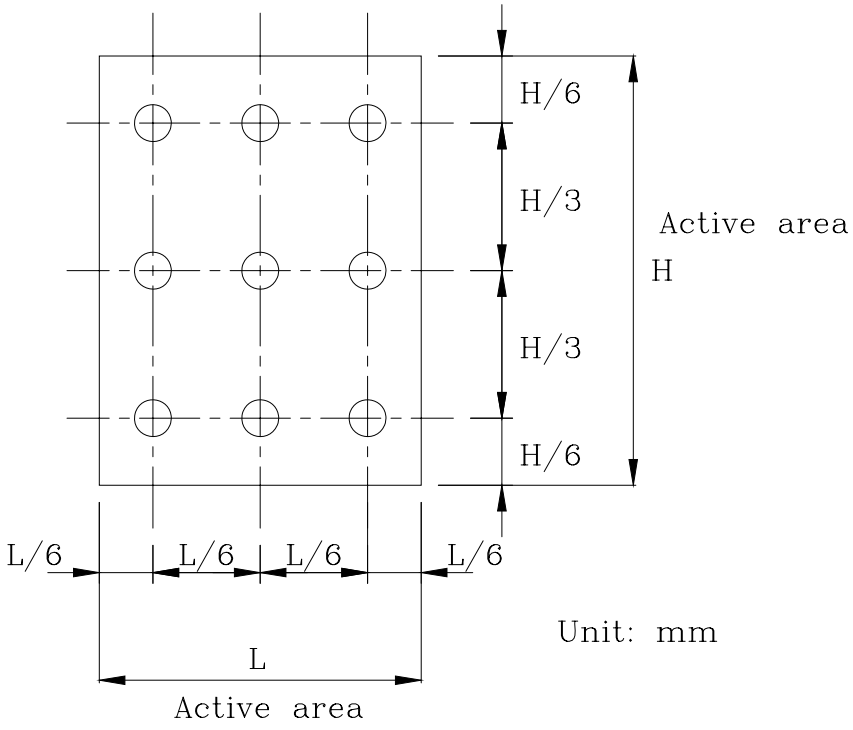
Note 4: Definition of Luminance

①The Brightness Test Equipment Setup

Field=2° (As measuring "black" image, field=2° is the best testing condition)

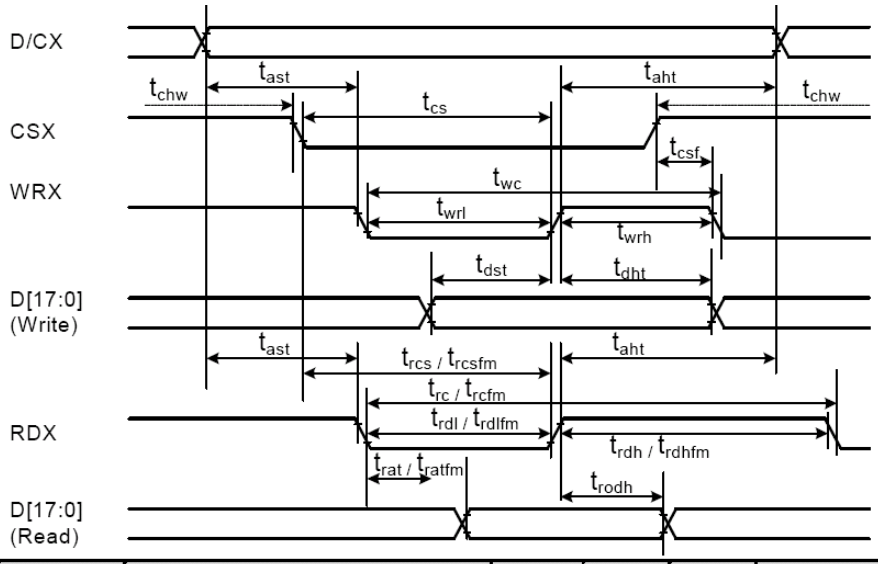


②The Brightness Test Point Setup



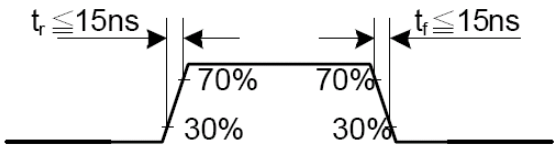
8. Timing Characteristics

8.1 Parallel 18/16/9/8-bit interface timing characteristics(80-I system)

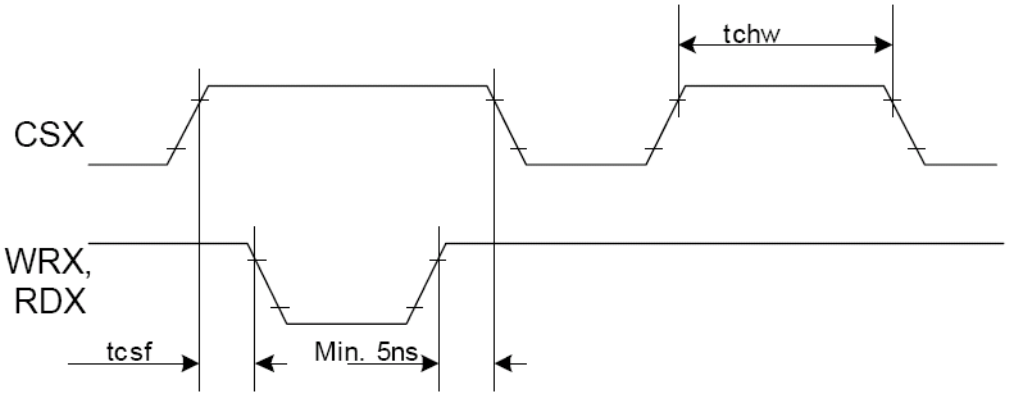


Signal	Symbol	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	
	taht	Address hold time (Write/Read)	0	-	ns	
CSX	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
	trcs	Chip Select setup time (Read ID)	45	-	ns	
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
WRX	twc	Write cycle	66	-	ns	
	twrh	Write Control pulse H duration	15	-	ns	
	twrl	Write Control pulse L duration	15	-	ns	
RDX (FM)	trcfm	Read Cycle (FM)	450	-	ns	
	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
RDX (ID)	trc	Read cycle (ID)	160	-	ns	
	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
D[17:0], D[15:0], D[8:0], D[7:0]	tdst	Write data setup time	10	-	ns	For maximum CL=30pF For minimum CL=8pF
	tdht	Write data hold time	10	-	ns	
	trat	Read access time	-	40	ns	
	tratfm	Read access time	-	340	ns	
	trod	Read output disable time	20	80	ns	

Note: Ta = -30 to 70 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, VSS=0V

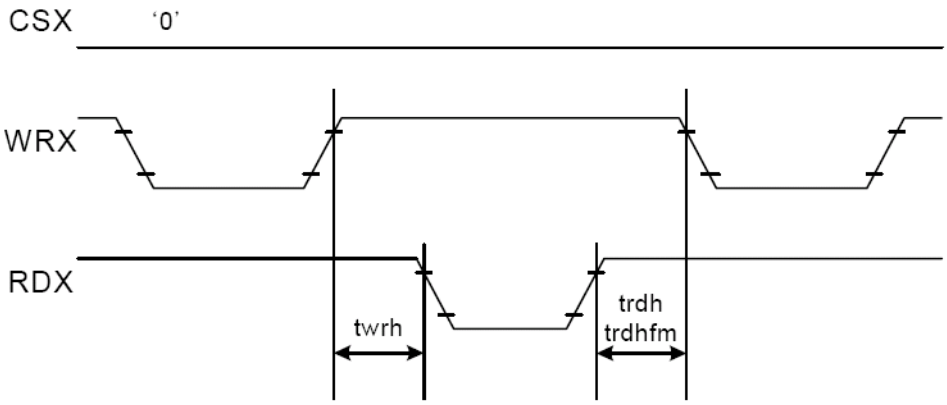


CSX timings :



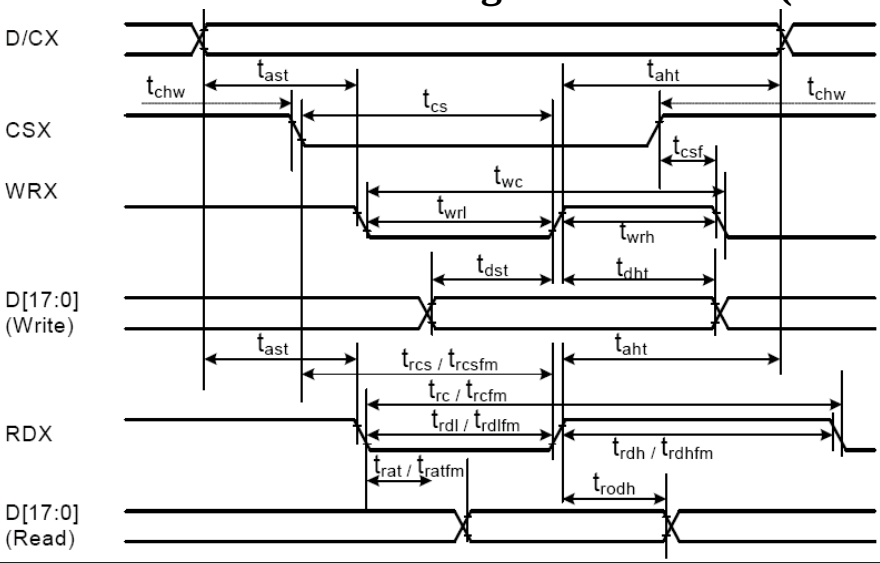
Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

Write to read or read to write timings:



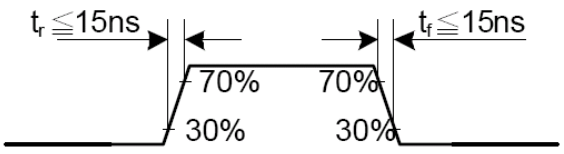
Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

8.2 Parallel 18/16/9/8-bit interface timing characteristics(80-Ⅱ system)

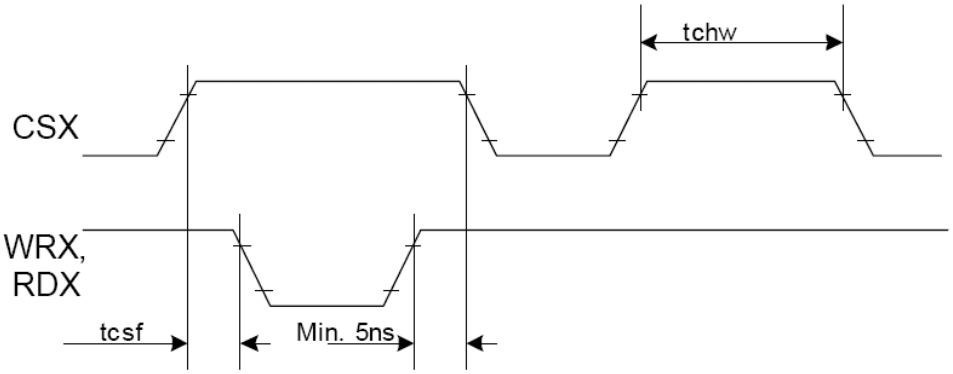


Signal	Symbol	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	
	taht	Address hold time (Write/Read)	0	-	ns	
CSX	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
	trcs	Chip Select setup time (Read ID)	45	-	ns	
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
WRX	twc	Write cycle	66	-	ns	
	twrh	Write Control pulse H duration	15	-	ns	
	twrl	Write Control pulse L duration	15	-	ns	
RDX (FM)	trcfm	Read Cycle (FM)	450	-	ns	
	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
RDX (ID)	trc	Read cycle (ID)	160	-	ns	
	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
D[17:0], D[17:10]&D[8:1], D[17:10], D[17:9]	tdst	Write data setup time	10	-	ns	For maximum CL=30pF For minimum CL=8pF
	tdht	Write data hold time	10	-	ns	
	trat	Read access time	-	40	ns	
	tratfm	Read access time	-	340	ns	
	trod	Read output disable time	20	80	ns	

Note: Ta = -30 to 70 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, VSS=0V.

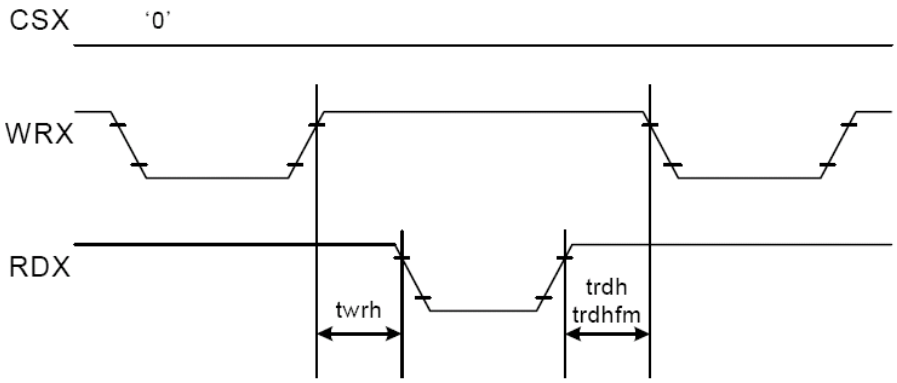


CSX timings :



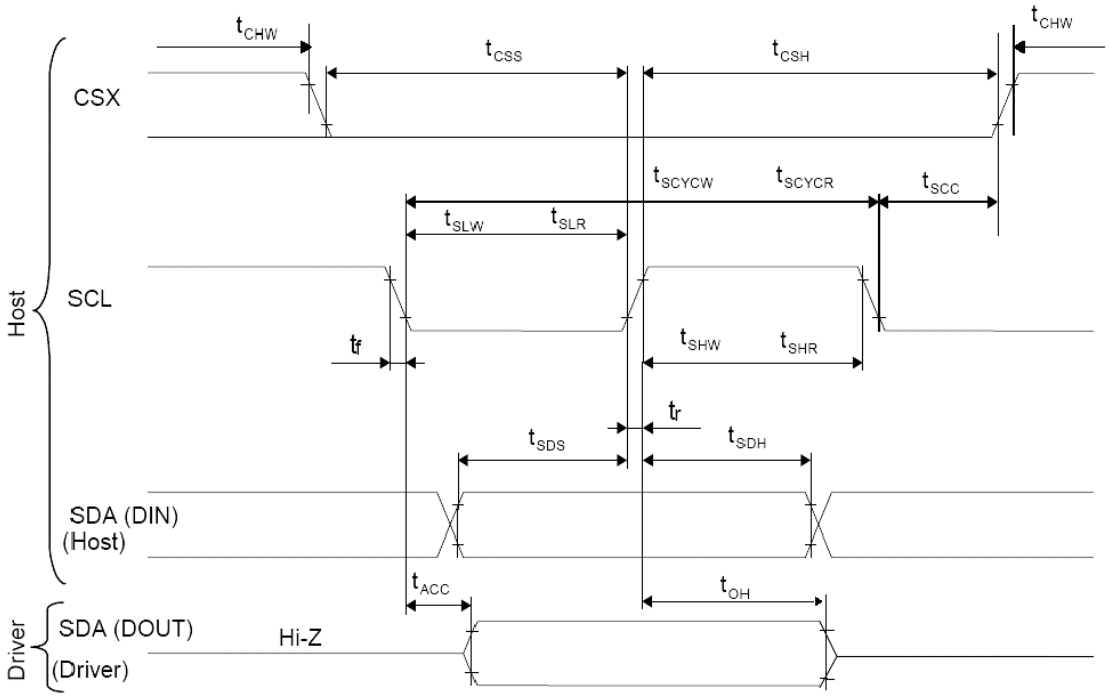
Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

Write to read or read to write timings:



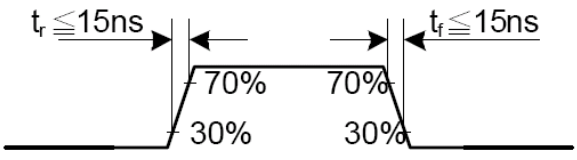
Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

8.3 Serial interface timing characteristics(3-line SPI system)

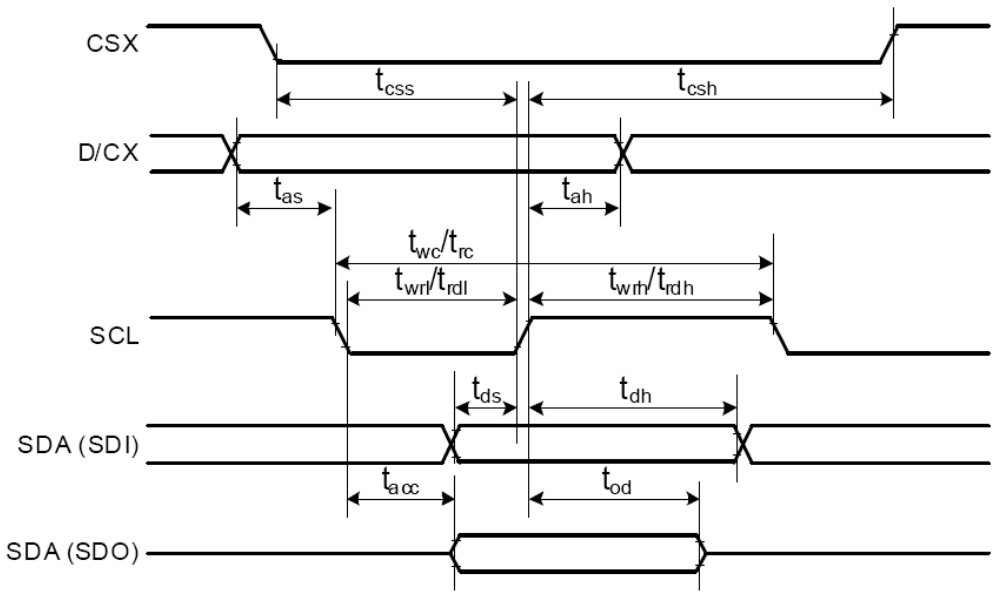


Signal	Symbol	Parameter	min	max	Unit	Description
SCL	tscycw	Serial Clock Cycle (Write)	100	-	ns	
	tshw	SCL “H” Pulse Width (Write)	40	-	ns	
	tslw	SCL “L” Pulse Width (Write)	40	-	ns	
	tscycr	Serial Clock Cycle (Read)	150	-	ns	
	tshr	SCL “H” Pulse Width (Read)	60	-	ns	
	tslr	SCL “L” Pulse Width (Read)	60	-	ns	
SDA / SDI (Input)	tsds	Data setup time (Write)	30	-	ns	
	tsdh	Data hold time (Write)	30	-	ns	
SDA / SDO (Output)	tacc	Access time (Read)	10	-	ns	
	toh	Output disable time (Read)	10	50	ns	
CSX	tscc	SCL-CSX	20	-	ns	
	tchw	CSX “H” Pulse Width	40	-	ns	
	tcss	CSX-SCL Time	60	-	ns	
	tcsh		65	-	ns	

Note: Ta = 25 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=VSS=0V

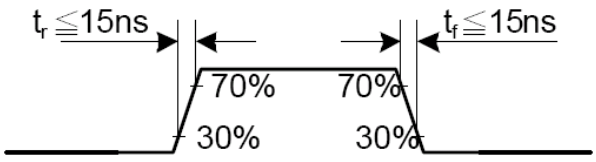


8.4 Serial interface timing characteristics(4-line SPI system)

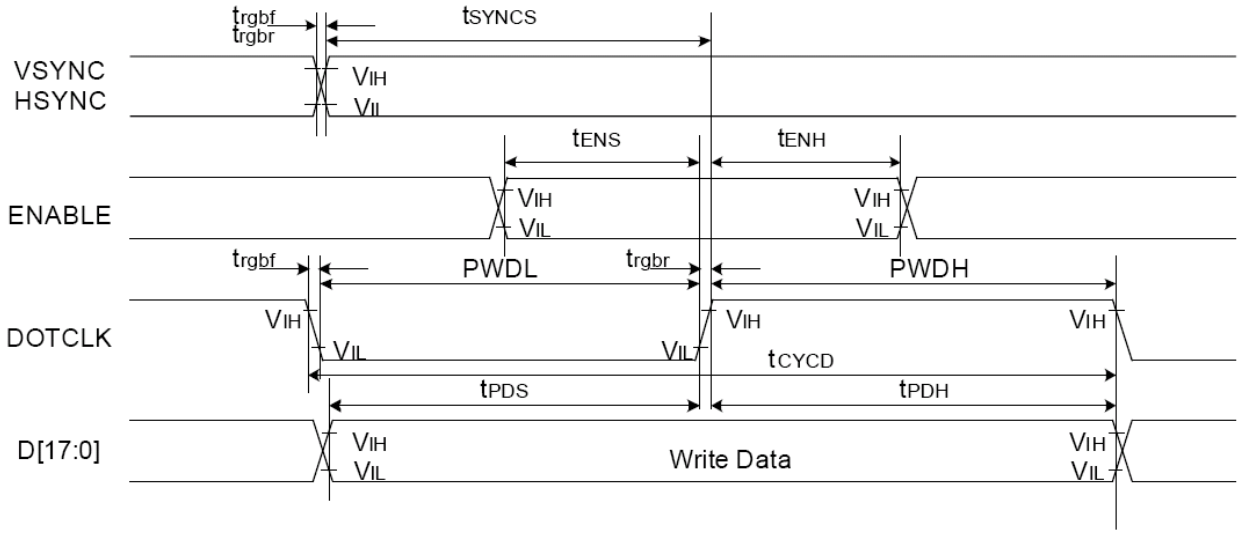


Signal	Symbol	Parameter	min	max	Unit	Description
CSX	tcss	Chip select time (Write)	40	-	ns	
	tcsh	Chip select hold time (Read)	40	-	ns	
SCL	twc	Serial clock cycle (Write)	100	-	ns	
	twrh	SCL “H” pulse width (Write)	40	-	ns	
	twrl	SCL “L” pulse width (Write)	40	-	ns	
	trc	Serial clock cycle (Read)	150	-	ns	
	trdh	SCL “H” pulse width (Read)	60	-	ns	
	trdl	SCL “L” pulse width (Read)	60	-	ns	
D/CX	tas	D/CX setup time	10	-		
	tah	D/CX hold time (Write / Read)	10	-		
SDA / SDI (Input)	tds	Data setup time (Write)	30	-	ns	
	tdh	Data hold time (Write)	30	-	ns	
SDA / SDO (Output)	tacc	Access time (Read)	10	-	ns	For maximum CL=30pF
	tod	Output disable time (Read)	10	50	ns	For minimum CL=8pF

Note: Ta = 25 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=VSS=0V

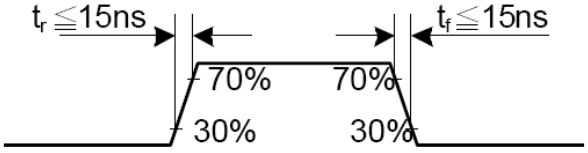


8.5 Parallel 18/16/6-bit RGB interface timing characteristics

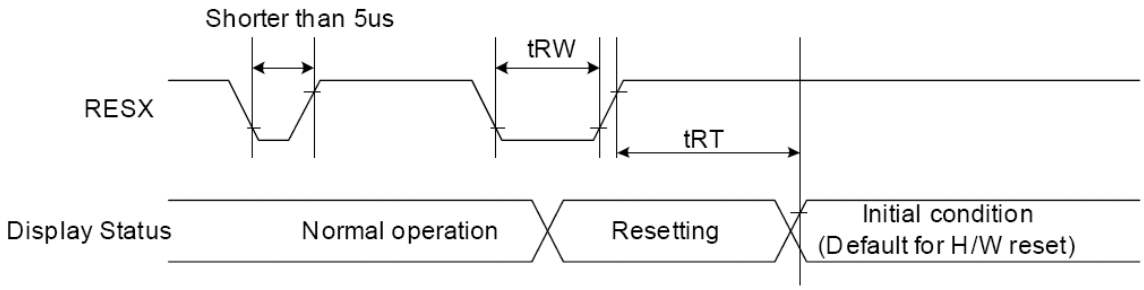


Signal	Symbol	Parameter	min	max	Unit	Description
VSYNC / HSYNC	t_{SYNCS}	VSYNC/HSYNC setup time	15	-	ns	18/16-bit bus RGB interface mode
	t_{SYNCH}	VSYNC/HSYNC hold time	15	-	ns	
DE	t_{ENS}	DE setup time	15	-	ns	
	t_{ENH}	DE hold time	15	-	ns	
D[17:0]	t_{POS}	Data setup time	15	-	ns	
	t_{PDH}	Data hold time	15	-	ns	
DOTCLK	PWDH	DOTCLK high-level period	15	-	ns	
	PWDL	DOTCLK low-level period	15	-	ns	
	t_{CYCD}	DOTCLK cycle time	100	-	ns	
	t_{rgbr} , t_{rgbf}	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	
VSYNC / HSYNC	t_{SYNCS}	VSYNC/HSYNC setup time	15	-	ns	6-bit bus RGB interface mode
	t_{SYNCH}	VSYNC/HSYNC hold time	15	-	ns	
DE	t_{ENS}	DE setup time	15	-	ns	
	t_{ENH}	DE hold time	15	-	ns	
D[17:0]	t_{POS}	Data setup time	15	-	ns	
	t_{PDH}	Data hold time	15	-	ns	
DOTCLK	PWDH	DOTCLK high-level pulse period	15	-	ns	
	PWDL	DOTCLK low-level pulse period	15	-	ns	
	t_{CYCD}	DOTCLK cycle time	50	-	ns	
	t_{rgbr} , t_{rgbf}	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	

Note: Ta = -30 to 70 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=VSS=0V



8.6 Reset timing



Signal	Symbol	Parameter	Min	Max	Unit
RESX	tRW	Reset pulse duration	10		uS
	tRT	Reset cancel		5 (note 1,5)	mS
				120 (note 1,6,7)	mS

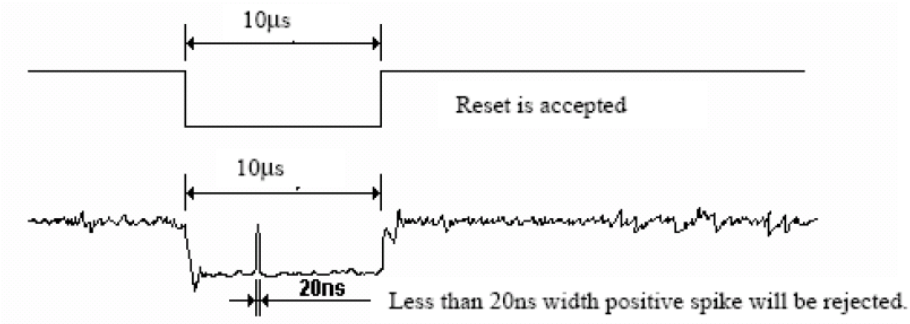
Note 1: The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NV memory to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

Note 2: Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below: -

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 10us	Reset
Between 5us and 10us	Reset starts

Note 3: During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In -mode.) And then return to Default condition for Hardware Reset.

Note 4: Spike Rejection also applies during a valid reset pulse as shown below:



Note 5: When Reset applied during Sleep In Mode.

Note 6: When Reset applied during Sleep Out Mode.

Note 7: It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

9. Standard Specification for Reliability

9.1 Standard Specification for Reliability of LCD Module

No.	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70℃ for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20℃ for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80℃ for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30℃ for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60℃,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles : -30℃ for 30 minutes → normal temperature for 5 minutes → +80℃ for 30 minutes → normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range : 10Hz ~ 55Hz Amplitude of vibration : 1.5mm Sweep time: 12 min X,Y,Z 2 hours for each direction.
08	Packing drop test	According to ASTM-D-5327.
09	Electrical Static Discharge	Air: ±4KV 150pF/330Ω 5 times
		Contact: ±2KV 150pF/330Ω 5 time

*Sample size for each test item is 3~5pcs

9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

9.3 MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature (25±5℃), normal humidity (50±10% RH), and in area not exposed to direct sun light.

10. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by Tecenstar.

10.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

10.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level Ⅱ take a single Time.
- The defects classify of AQL as following:
  Major defect: AQL = 0.65
  Minor defect: AQL = 2.5
  Total defects: AQL = 2.5

10.3 Non-conforming Analysis & Deal With Manners

10.3.1 Non-conforming Analysis

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

10.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

10.4 Agreement items

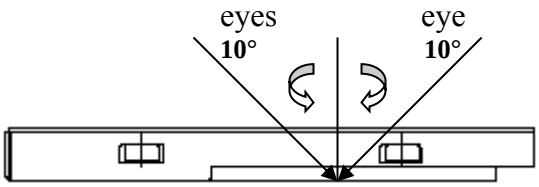
Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

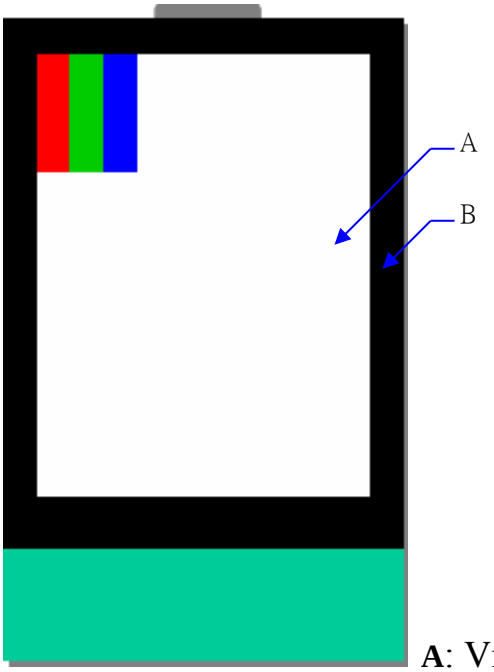
10.5 Standard of The Product Appearance Test

10.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 10° of vertical line.
- Temperature: 25±5℃ Humidity: 60±10%RH



- Definition of area:

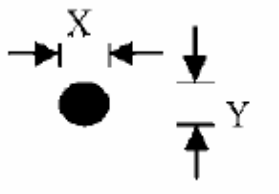


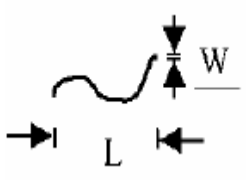
A: Viewing area B: Outside viewing area

10.5.2 Basic principle

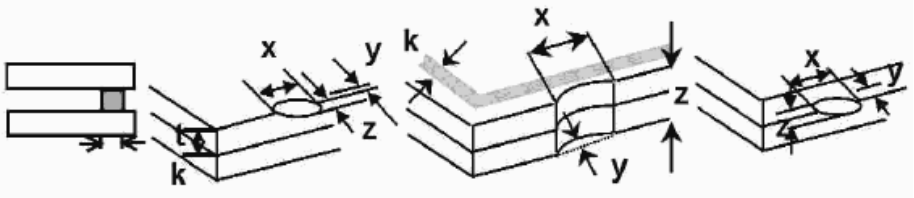
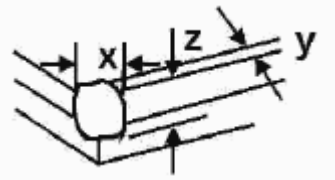
- When the standard can not be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.
- New item must be added on time when it is necessary.

10.6 Inspection Specification

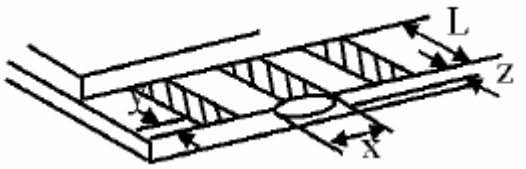
<table>
<tr><th>NO.</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>01</td><td>Electrical Testing</td><td>1.1 Missing vertical, horizontal segment, segment contrast defect.
1.2 Missing character, dot or icon.
1.3 Display malfunction.
1.4 No function or no display.
1.5 Current consumption exceeds product specifications.
1.6 LCD viewing angle defect.
1.7 Mixed product types.
1.8 Flicker</td><td>0.65</td></tr>
<tr><td>02</td><td>Black or White spots or Bright spots or Color spots on LCD (Display only)</td><td>2.1 White and black or color spots on display ≦ 0.25mm, no more than Five spots.
2.2 Densely spaced: No more than three spots within 3mm.</td><td>2.5</td></tr>
<tr><td rowspan="2">03</td><td rowspan="2">LCD and Touch Panel black spots, white spots, contamination (non – display)</td><td>3.1 Round type: As following drawing
Φ = (X+Y) / 2
 

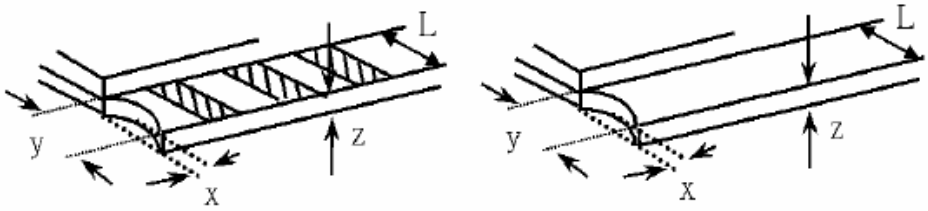
<table>
<tr><th>Size(mm)</th><th>Acceptable Q'ty</th></tr>
<tr><td>Φ≦0.10</td><td>Accept no dense</td></tr>
<tr><td>0.10< Φ≦0.20</td><td>2</td></tr>
<tr><td>0.20< Φ≦0.25</td><td>2</td></tr>
<tr><td>0.25< Φ≦0.30</td><td>1</td></tr>
<tr><td>0.30< Φ</td><td>0</td></tr>
</table>
* Densely spaced: No more than two spots within 3mm.</td><td>2.5</td></tr>
<tr><td>3.2 Line type: (As following drawing)
 

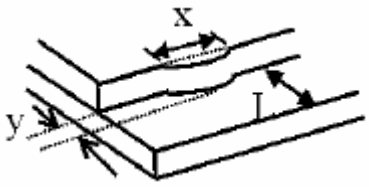
<table>
<tr><th>Length(mm)</th><th>Width(mm)</th><th>Acceptable Q'ty</th></tr>
<tr><td>---</td><td>W≦0.02</td><td>Accept no dense</td></tr>
<tr><td>L≦3.0</td><td>0.02<W≦0.05</td><td rowspan="2">2</td></tr>
<tr><td>L≦2.5</td><td>0.03<W≦0.08</td></tr>
<tr><td>---</td><td>0.08<W</td><td>Rejection</td></tr>
</table>
* Densely spaced: No more than two lines within 3mm.</td><td>2.5</td></tr>
</table>

<table>
<tr><th>NO.</th><th>Item</th><th colspan="3">Criterion</th><th>AQL</th></tr>
<tr><td>04</td><td>Polarizer bubbles</td><td colspan="2">If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction
<table><tr><td>Size Φ(mm)</td><td>Acceptable Q'ty</td></tr><tr><td>Φ≦0.20</td><td>Accept no dense</td></tr><tr><td>0.20< Φ≦0.50</td><td>3</td></tr><tr><td>0.50< Φ≦1.00</td><td>2</td></tr><tr><td>1.00< Φ</td><td>0</td></tr><tr><td>Total Q’ty</td><td>3</td></tr></table></td><td></td><td>2.5</td></tr>
<tr><td>05</td><td>Scratches</td><td colspan="3">Follow NO.3 -2 Line Type.</td><td></td></tr>
<tr><td>06</td><td>Chipped glass</td><td colspan="3">Symbols:
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length
6.1 General glass chip:
6.1.1 Chip on panel surface and crack between panels:
 
<table><tr><td>z: Chip thickness</td><td>y: Chip width</td><td>x: Chip length</td></tr><tr><td>Z≦1/2t</td><td>Not over viewing area</td><td>x≦1/8a</td></tr><tr><td>1/2t< z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr></table>⊙ Unit: mm
⊙ If there are 2 or more chips, x is the total length of each chip
6.1.2 Corner crack:
 
<table><tr><td>z: Chip thickness</td><td>y: Chip width</td><td>x: Chip length</td></tr><tr><td>Z≦1/2t</td><td>Not over viewing area</td><td>x≦1/8a</td></tr><tr><td>1/2t< z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr></table>⊙ Unit: mm
⊙ If there are 2 or more chips, x is the total length of each chip</td><td>2.5</td></tr>
</table>

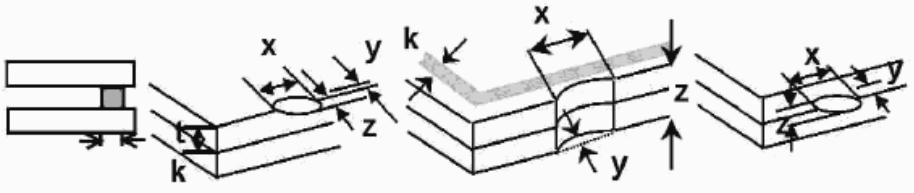
NO.	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
09	Backlight elements	9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong.	2.5 2.5 0.65
10	Bezel	Bezel must comply with product specifications.	2.5
11	PCB、COB	11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart.	2.5 2.5 2.5 2.5 0.65 0.65
12	FPC	12.1 FPC terminal damage ≦ 1/2 FPC terminal width and can not affect the function , we judge accept. 12.2 FPC alignment hole damage ≦ 1/2 alignment area and can not affect the function , we judge accept.	2.5 2.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle. 13.2 No short circuits in components on PCB or FPC.	2.5 0.65

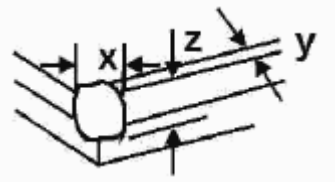
<table>
<tr><th>NO.</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>07</td><td>Glass crack</td><td>
Symbols:
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length
7.2 Protrusion over terminal:
7.2.1 Chip on electrode pad:


<table>
<tr><td>y: Chip width</td><td>x: Chip length</td><td>z: Chip thickness</td></tr>
<tr><td>y≦0.5mm</td><td>x≦1/8a</td><td>0< z≦t</td></tr>
</table>
7.2.2
Non-conductive portion:


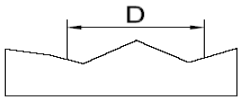
<table>
<tr><td>y: Chip width</td><td>x: Chip length</td><td>z: Chip thickness</td></tr>
<tr><td>y≦L</td><td>x≦1/8a</td><td>0< z≦t</td></tr>
</table>
⊙ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.
⊙ If the product will be heat sealed by the customer, the alignment mark must mot be damaged.
7.2.3 Substrate protuberance and internal crack


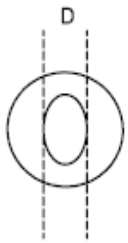
<table>
<tr><td>y: width</td><td>x: length</td></tr>
<tr><td>y≦1/3L</td><td>X≦a</td></tr>
</table>
</td><td>2.5</td></tr>
</table>

<table>
<tr><th>NO.</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>14</td><td>Touch Panel
Chipped
glass</td><td>
Symbols:
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Touch Panel Total thickness a: LCD side length
L: Electrode pad length
14.1 General glass chip:
14.1.1 Chip on panel surface and crack between panels:


<table>
<tr><td>z: Chip thickness</td><td>y: Chip width</td><td>x: Chip length</td></tr>
<tr><td>Z≦t</td><td>≦1/2 k and not over viewing area</td><td>x≦1/8a</td></tr>
</table>
⊙ Unit: mm
⊙ If there are 2 or more chips, x is the total length of each chip
14.1.2 Corner crack:


<table>
<tr><td>z: Chip thickness</td><td>y: Chip width</td><td>x: Chip length</td></tr>
<tr><td>z≦t</td><td>≦1/2 k and not over viewing area</td><td>x≦1/8a</td></tr>
</table>
⊙ Unit: mm
⊙ If there are 2 or more chips, x is the total length of each chip
</td><td>2.5</td></tr>
</table>

<table>
<tr><th>NO.</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>15</td><td>Touch Panel(Fish eye、dent and bubble on film)</td><td>
<table>
<tr><td>SIZE(mm)</td><td>Acceptable Q’ty</td></tr>
<tr><td>Φ≦0.2</td><td>Accept no dense</td></tr>
<tr><td>0.2< D ≦0.4</td><td>5</td></tr>
<tr><td>0.4< D ≦0.5</td><td>2</td></tr>
<tr><td>0.5< D</td><td>0</td></tr>
</table>




</td><td>2.5</td></tr>
<tr><td>16</td><td>Touch Panel Newton ring</td><td>Newton ring dimension ≦ 1/2 touch panel area and not affect font and line distortion(≦2.5%) , it is acceptable.</td><td>2.5</td></tr>
<tr><td>17</td><td>Touch Panel Linearity</td><td>Less than 2.5% is acceptable.</td><td>2.5</td></tr>
<tr><td>18</td><td>LCD Ripple</td><td>Touch the touch panel , can not see the LCD ripple.
Pen: R 1.0mm silicon rubber.
Operation Force: 80g</td><td>2.5</td></tr>
<tr><td>19</td><td>General appearance</td><td>19.1 Pin type must match type in specification sheet.
19.2 LCD pin loose or missing pins.
19.3 Product packaging must the same as specified on packaging specification sheet.
19.4 Product dimension and structure must conform to product specification sheet.</td><td>0.65
0.65
0.65
0.65</td></tr>
</table>

11. Handling Precaution

11.1 Handling of LCM

- Avoid external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

11.2 Storage

- Store it in an ambient temperature of 25±10℃, and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Store it in a clean environment, free from dust, active gas, and solvent.
- Store it in anti-static electricity container.
- Store it without any physical load.

11.3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: no higher than 280±10℃ and less than 3 sec during hand soldering.
- Rewiring: no more than 2 times.

12. Packing Method

----TBD